

V <sub>DSS</sub>	250V
R <sub>DS(on)</sub> (Max.)	530m $\Omega$
I <sub>D</sub>	6A
P <sub>D</sub>	52W

### Features

- 1) Low on-resistance.
- 2) Fast switching speed.
- 3) Drive circuits can be simple.
- 4) Parallel use is easy.
- 5) Pb-free lead plating ; RoHS compliant
- 6) 100% Avalanche tested

# Application

Switching Power Supply

Automotive Motor Drive

Automotive Solenoid Drive

# •Absolute maximum ratings ( $T_a = 25^{\circ}C$ )

# (SC-63) <SOT-428> (1) (2) (3) (2) (3) (2) (3) (1) Gate (2) Drain (3) Source \*1 BODY DIODE

# Packaging specifications.

Outline

СРТ3

	Packaging	Taping
	Reel size (mm)	330
Tuno	Tape width (mm)	16
Туре	Basic ordering unit (pcs)	2,500
	Taping code	TL
	Marking	C06N25

Parametér		Symbol	Value	Unit
Drain - Source voltage		V <sub>DSS</sub>	250	V
Continuous drain current	T <sub>c</sub> = 25°C	ا <sub>D</sub> *1	±6	А
	T <sub>c</sub> = 100°C	۱ <sub>D</sub> *1	±3.3	А
Pulsed drain current		I <sub>D,pulse</sub> *2	±24	А
Gate - Source voltage	V <sub>GSS</sub>	±30	V	
Avalanche energy, single pulse	Avalanche energy, single pulse			mJ
Avalanche current		I <sub>AS</sub> *3	3	А
Power dissipation	$T_c = 25^{\circ}C$	P <sub>D</sub>	52	W
	$T_a = 25^{\circ}C^{*4}$	P <sub>D</sub>	0.85	W
Junction temperature	Tj	150	°C	
Range of storage temperature		T <sub>stg</sub>	-55 to +150	°C

### Thermal resistance

Parameter	Symbol		Unit			
Farameter	Symbol	Min.	Тур.	Max.	Unit	
Thermal resistance, junction - case	R <sub>thJC</sub>	-	-	2.36	°C/W	
Thermal resistance, junction - ambient *4	R <sub>thJA</sub>	-	-	147	°C/W	
Soldering temperature, wavesoldering for 10s	T <sub>sold</sub>	-	-	265	°C	

# ●Electrical characteristics (T<sub>a</sub> = 25°C)

	,					
Parameter	Symbol Conditions		Values			Unit
Falameter	Symbol	Conditions	Min.	Тур.	Max.	Onin
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 1mA$	250	-	-	V
		$V_{DS} = 250V, V_{GS} = 0V$			10	
Zero gate voltage	<b>.</b>	T <sub>j</sub> = 25°C	_		10	۸
drain current	I <sub>DSS</sub>	$V_{DS} = 250V, V_{GS} = 0V$			100	μA
		T <sub>j</sub> = 125°C		-	100	
Gate - Source leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 30V, V_{DS} = 0V$	-	-	±100	nA
Gate threshold voltage	V <sub>GS (th)</sub>	$V_{DS} = 10V, I_D = 1mA$	3.0	-	5.0	V
	R <sub>DS(on)</sub> *5	$V_{GS} = 10V, I_{D} = 3.0A$	-	410	530	
Static drain - source on - state resistance		$V_{GS} = 10V, I_{D} = 3.0A$	_	930	1200	mΩ
		T <sub>j</sub> = 125°C		900	1200	
Forward transfer admittance	g <sub>fs</sub>	$V_{DS} = 10V, I_{D} = 3.0A$	2.2	4.4	-	S

# ●Electrical characteristics (T<sub>a</sub> = 25°C)

Parameter	Symbol	Conditions	Values			Unit
Farameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Input capacitance	C <sub>iss</sub>	$V_{GS} = 0V$	-	840	-	
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 25V	-	50	-	pF
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	25		
Turn - on delay time	t <sub>d(on)</sub> *5	$V_{DD} \simeq 125 V, V_{GS} = 10 V$	-	22		
Rise time	t <sub>r</sub> *5	I <sub>D</sub> = 3A	-	20	-	
Turn - off delay time	t <sub>d(off)</sub> *5	R <sub>L</sub> = 41.67Ω	- (	30	-	ns
Fall time	t <sub>f</sub> *5	$R_{G} = 10\Omega$		13	-	

# •Gate Charge characteristics (T<sub>a</sub> = 25°C)

•Gate Charge characteristics	(T <sub>a</sub> = 25°C)					
Parameter	Symbol	Conditions	Min.	Values Typ.	Max.	Unit
Total gate charge	Qg <sup>*5</sup>	V <sub>DD</sub> ≃ 125V		15	-	
Gate - Source charge	Q <sub>gs</sub> <sup>*5</sup>	1 <sub>D</sub> = 6A	-	6	-	nC
Gate - Drain charge	Q <sub>gd</sub> <sup>*5</sup>	V <sub>GS</sub> = 10V	-	6	-	
Gate plateau voltage	V <sub>(plateau)</sub>	$V_{DD} \simeq 125 V, I_D = 6 A$	-	7.5	-	V

# ●Body diode electrical characteristics (Source-Drain)(T<sub>a</sub> = 25°C)

Parameter	Symbol	Conditions	Values			Unit	
Falanielei	Symbol	Conditions	Min.	Тур.	Max.	Onit	
Continuous source current	I <sub>S</sub> *1	T <sub>c</sub> = 25°C	-	-	6	А	
Pulsed source current	I <sub>SM</sub> *2	1 <sub>c</sub> = 25 C	-	-	24	А	
Forward voltage	$V_{SD}$ *5	$V_{GS} = 0V, I_{S} = 6.0A$	-	-	1.5	V	
Reverse recovery time	t <sub>rr</sub> *5	I <sub>S</sub> = 3.0A	-	85	-	ns	
Reverse recovery charge	Q <sub>rr</sub> <sup>*5</sup>	di/dt = 100A/µs	-	250	-	nC	

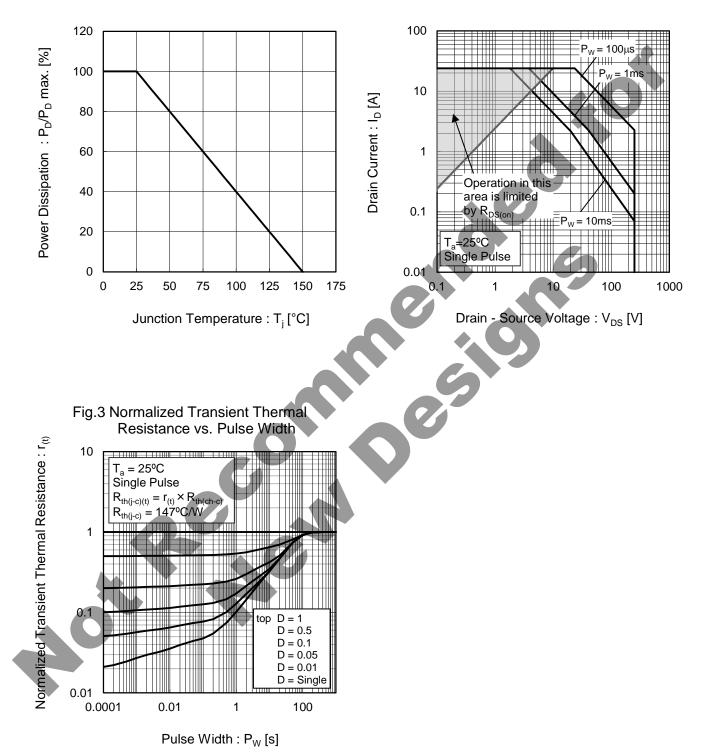
\*1 Limited only by maximum temperature allowed.

\*2 Pw  $\leq$  10  $\mu s,$  Duty cycle  $\leq$  1%

\*3 L  $\simeq$  500 $\mu$ H, V<sub>DD</sub> = 50V, Rg = 25 $\Omega$ , starting T<sub>j</sub> = 25°C

\*4 Mounted on a epoxy PCB FR4 (20mm × 30mm × 0.8mm)

\*5 Pulsed



# Fig.1 Power Dissipation Derating Curve

Fig.2 Maximum Safe Operating Area

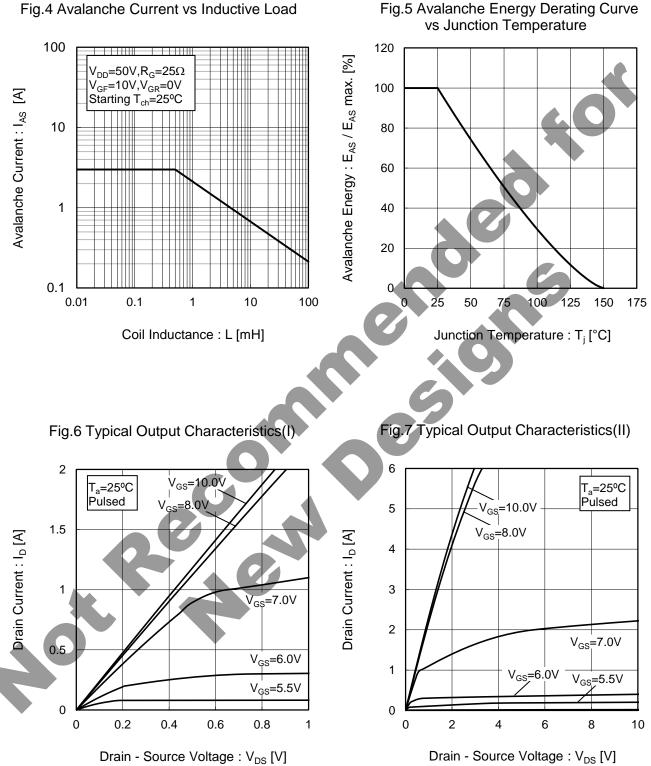
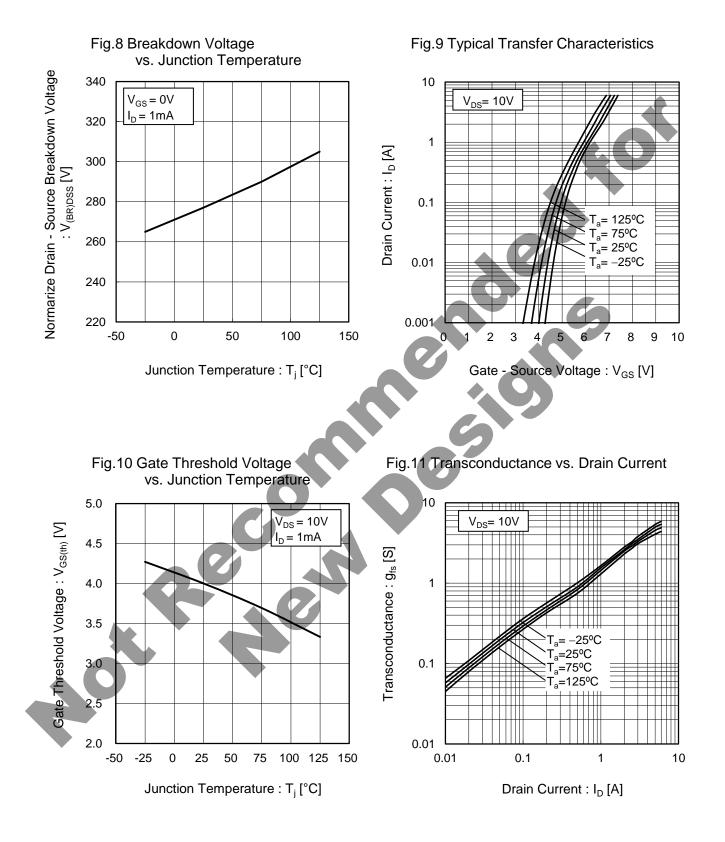
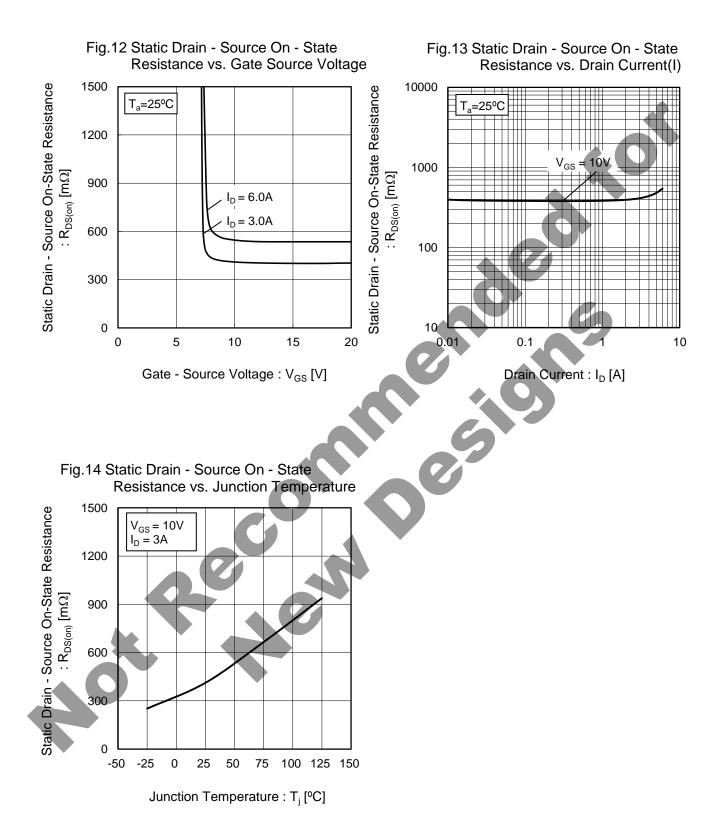
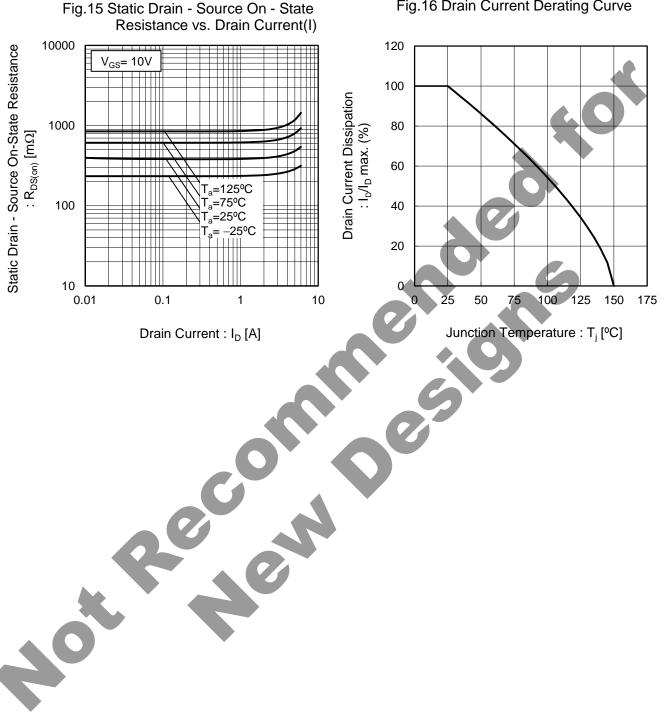
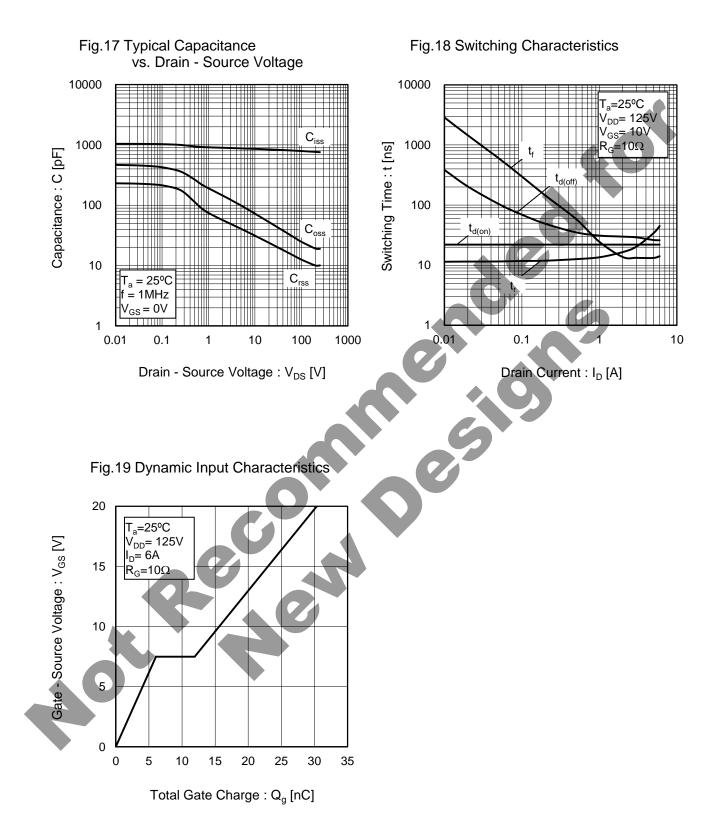


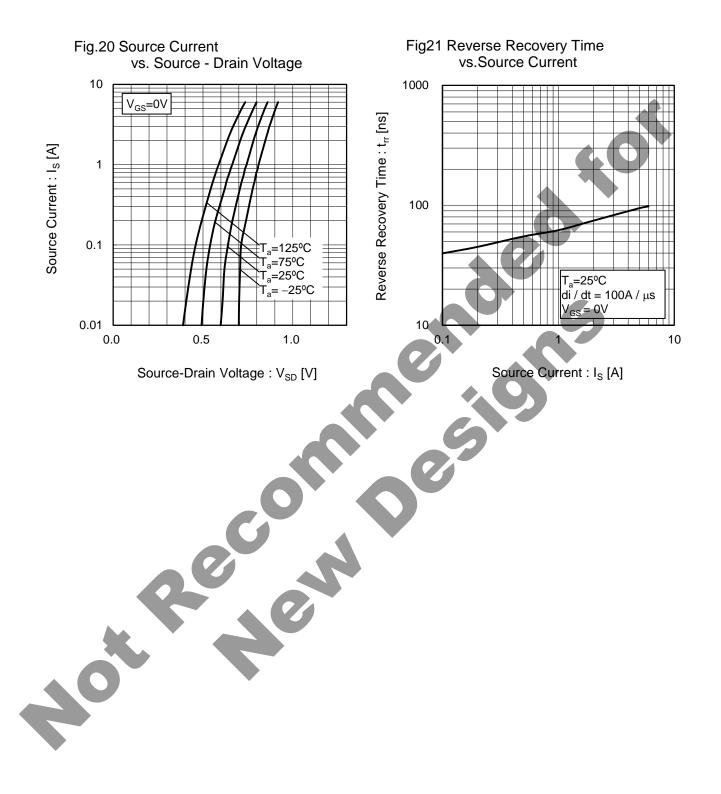
Fig.4 Avalanche Current vs Inductive Load













# Measurement circuits

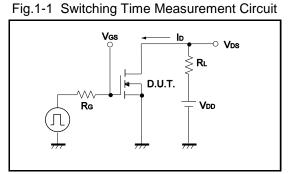


Fig.2-1 Gate Charge Measurement Circuit

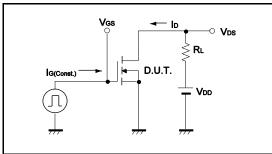


Fig.3-1 Avalanche Measurement Circuit

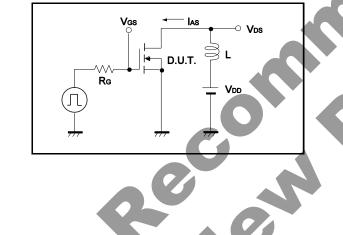


Fig.1-2 Switching Waveforms

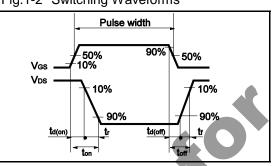


Fig.2-2 Gate Charge Waveform

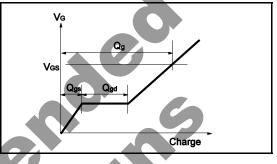
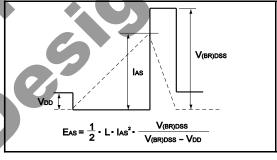


Fig.3-2 Avalanche Waveform

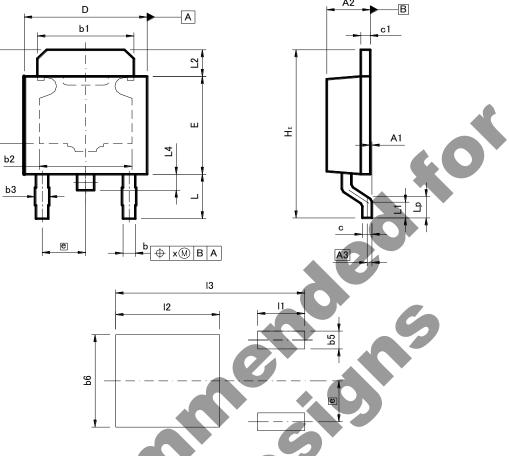


40

# •Dimensions (Unit : mm)

2

# CPT3



A2

DIM	MILIMI	ETERS	INCI	HES	
DIN	MIN	MAX	MIN	MAX	
A1	0.00	0.15	0	0.006	
A2	2,20	2.50	0.087	0.098	
A3	0.:	25	0.0	)1	
b	0.55	0.75	0.022	0.03	
b1	5.00	<u>5.3</u> 0	0.197	0.209	
b2	5.0	00	0.2	20	
b3	0.75		0.0	)3	
0	0.40	0.60	0.016	0.024	
c1	0.40	0.60	0.016	0.024	
D	6.30	6.70	0.248	0.264	
E	5.40	5.80	0.213	0.228	
e	2.3	30	0.09		
HE	9.00	10.00	0.354	0.394	
L	2.20	2.80	0.087	0.11	
L1	0.80	1.40	0.031	0.055	
L2	1.20	1.80	0.047	0.071	
L3	5.3	30	0.2	09	
L4	0.9	90	0.0	35	
Lp	1.00	1.60	0.039	0.063	
х	-	0.25	_	0.01	

DIM	MILIM	ETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
b5	-	1.00	-	0.04	
b6	-	5.20	-	0.205	
11	-	2.50	-	0.098	
12	-	5.50	-	0.217	
13	-	10.00	-	0.394	

Dimension in mm/inches

20%

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(Note1)	Medical	Equi	pment Classifi	cation of the	Spec	ific Applications	
1.0						CLUNA	Ξ

JAPAN	USA	EU	CHINA
CLASSⅢ		CLASS II b	
CLASSⅣ	CLASSⅢ	CLASSⅢ	CLASSI

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- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power, exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.

De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.

- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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For details, please refer to ROHM Mounting specification

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
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- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
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